



FSB52006S

Smart Power Module (SPM)

Features

- 60V, $R_{DS(ON),MAX}=80m\Omega$ @ 25°C 3-phase FRFET inverter including high voltage integrated circuit (HVIC)
- 3 divided negative dc-link terminals for inverter current sensing applications
- HVIC for gate driving and undervoltage protection
- 3/5V CMOS/TTL compatible, active-high interface
- Optimized for low electromagnetic interference
- Isolation voltage rating of 1500Vrms for 1min.
- Surface mounted device package
- Moisture Sensitive Level 3

General Description

FSB52006S is a tiny smart power module (SPM) based on FRFET technology as a compact inverter solution for small power motor drive applications such as fan motors and water suppliers. It is composed of 6 fast-recovery MOSFET (FRFET), and 3 half-bridge HVICs for FRFET gate driving. FSB52006S provides low electromagnetic interference (EMI) characteristics with optimized switching speed. Moreover, since it employs FRFET as a power switch, it has much better ruggedness and larger safe operation area (SOA) than that of an IGBT-based power module or one-chip solution. The package is optimized for the thermal performance and compactness for the use in the built-in motor application and any other application where the assembly space is concerned. FSB52006S is the most solution for the compact inverter providing the energy efficiency, compactness, and low electromagnetic interference.



Absolute Maximum Ratings

| Symbol | Parameter | Conditions | Rating | Units |
|-----------------|--|--|---------------------|-----------|
| V_{PN} | DC Link Input Voltage, Drain-source Voltage of each FRFET | | 60 | V |
| I_{D25} | Each FRFET Drain Current, Continuous | $T_C = 25^\circ\text{C}$ | 2.6 | A |
| I_{D100} | Each FRFET Drain Current, Continuous | $T_C = 100^\circ\text{C}$ | 1.3 | A |
| I_{DP} | Each FRFET Drain Current, Peak | $T_C = 25^\circ\text{C}$, $PW < 100\mu\text{s}$ | 5 | A |
| P_D | Maximum Power Dissipation | $T_C = 25^\circ\text{C}$, Each FRFET | 11 | W |
| V_{CC} | Control Supply Voltage | Applied between V_{CC} and COM | 20 | V |
| V_{BS} | High-side Bias Voltage | Applied between $V_{B(U)}-V_{S(U)}$, $V_{B(V)}-V_{S(V)}$, $V_{B(W)}-V_{S(W)}$ | 20 | V |
| V_{IN} | Input Signal Voltage | Applied between IN and COM | -0.3 ~ $V_{CC}+0.3$ | V |
| T_J | Operating Junction Temperature | | -20 ~ 125 | °C |
| T_{STG} | Storage Temperature | | -50 ~ 150 | °C |
| $R_{\theta JC}$ | Junction to Case Thermal Resistance | Each FRFET under inverter operating condition (Note 1) | 9.2 | °C/W |
| V_{ISO} | Isolation Voltage | 60Hz, Sinusoidal, 1 minute, Connection pins to heatsink | 1500 | V_{rms} |



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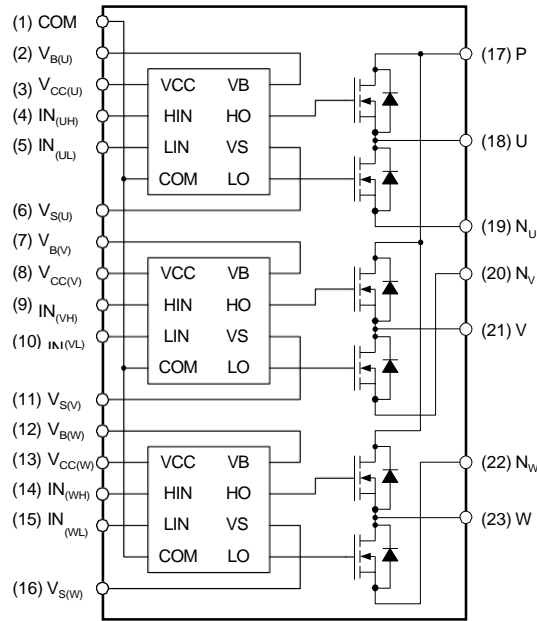


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Pin Descriptions

| Pin Number | Pin Name | Pin Description |
|------------|---------------|--|
| 1 | COM | IC Common Supply Ground |
| 2 | $V_{B(U)}$ | Bias Voltage for U Phase High Side FRFET Driving |
| 3 | $V_{CC(U)}$ | Bias Voltage for U Phase IC and Low Side FRFET Driving |
| 4 | $IN_{(UH)}$ | Signal Input for U Phase High-side |
| 5 | $IN_{(UL)}$ | Signal Input for U Phase Low-side |
| 6 | $V_{S(U)}$ | Bias Voltage Ground for U Phase High Side FRFET Driving |
| 7 | $V_{B(V)}$ | Bias Voltage for V Phase High Side FRFET Driving |
| 8 | $V_{CC(V)}$ | Bias Voltage for V Phase IC and Low Side FRFET Driving |
| 9 | $IN_{(VH)}$ | Signal Input for V Phase High-side |
| 10 | $IN_{(VL)}$ | Signal Input for V Phase Low-side |
| 11 | $V_{S(V)}$ | Bias Voltage Ground for V Phase High Side FRFET Driving |
| 12 | $V_{B(W)}$ | Bias Voltage for W Phase High Side FRFET Driving |
| 13 | $V_{CC(W)}$ | Bias Voltage for W Phase IC and Low Side FRFET Driving |
| 14 | $IN_{(WH)}$ | Signal Input for W Phase High-side |
| 15 | $IN_{(WL)}$ | Signal Input for W Phase Low-side |
| 16 | $V_{S(W)}$ | Bias Voltage Ground for W Phase High Side FRFET Driving |
| 17 | P | Positive DC-Link Input |
| 18 | U, $V_{S(U)}$ | Output for U Phase & Bias Voltage Ground for High Side FRFET Driving |
| 19 | N_U | Negative DC-Link Input for U Phase |
| 20 | N_V | Negative DC-Link Input for V Phase |
| 21 | V, $V_{S(V)}$ | Output for V Phase & Bias Voltage Ground for High Side FRFET Driving |
| 22 | N_W | Negative DC-Link Input for W Phase |
| 23 | W, $V_{S(W)}$ | Output for W Phase & Bias Voltage Ground for High Side FRFET Driving |



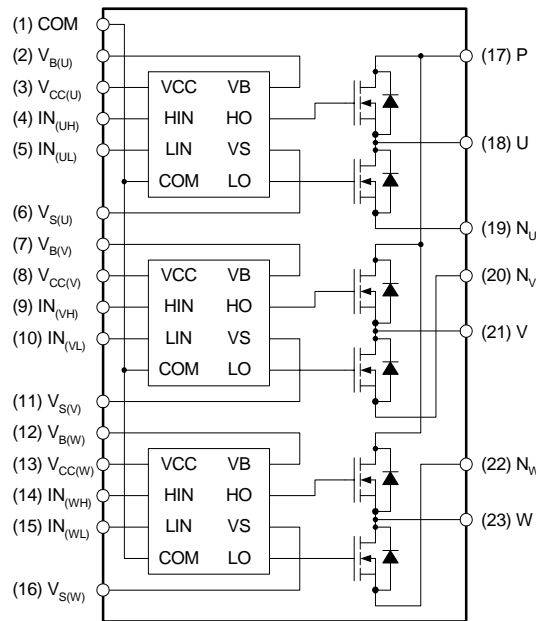
Note:

Source terminal of each MOSFET is not connected to supply ground or bias voltage ground inside SPM. External connections should be made as indicated in Figure 2 and 5.

Figure 1. Pin Configuration and Internal Block Diagram (Bottom View)

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| Pin Number | Pin Name | Pin Description |
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| 17 | P | Positive DC-Link Input |
| 18 | U, $V_{S(U)}$ | Output for U Phase & Bias Voltage Ground for High Side FRFET Driving |
| 19 | N_U | Negative DC-Link Input for U Phase |
| 20 | N_V | Negative DC-Link Input for V Phase |
| 21 | V, $V_{S(V)}$ | Output for V Phase & Bias Voltage Ground for High Side FRFET Driving |
| 22 | N_W | Negative DC-Link Input for W Phase |
| 23 | W, $V_{S(W)}$ | Output for W Phase & Bias Voltage Ground for High Side FRFET Driving |



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